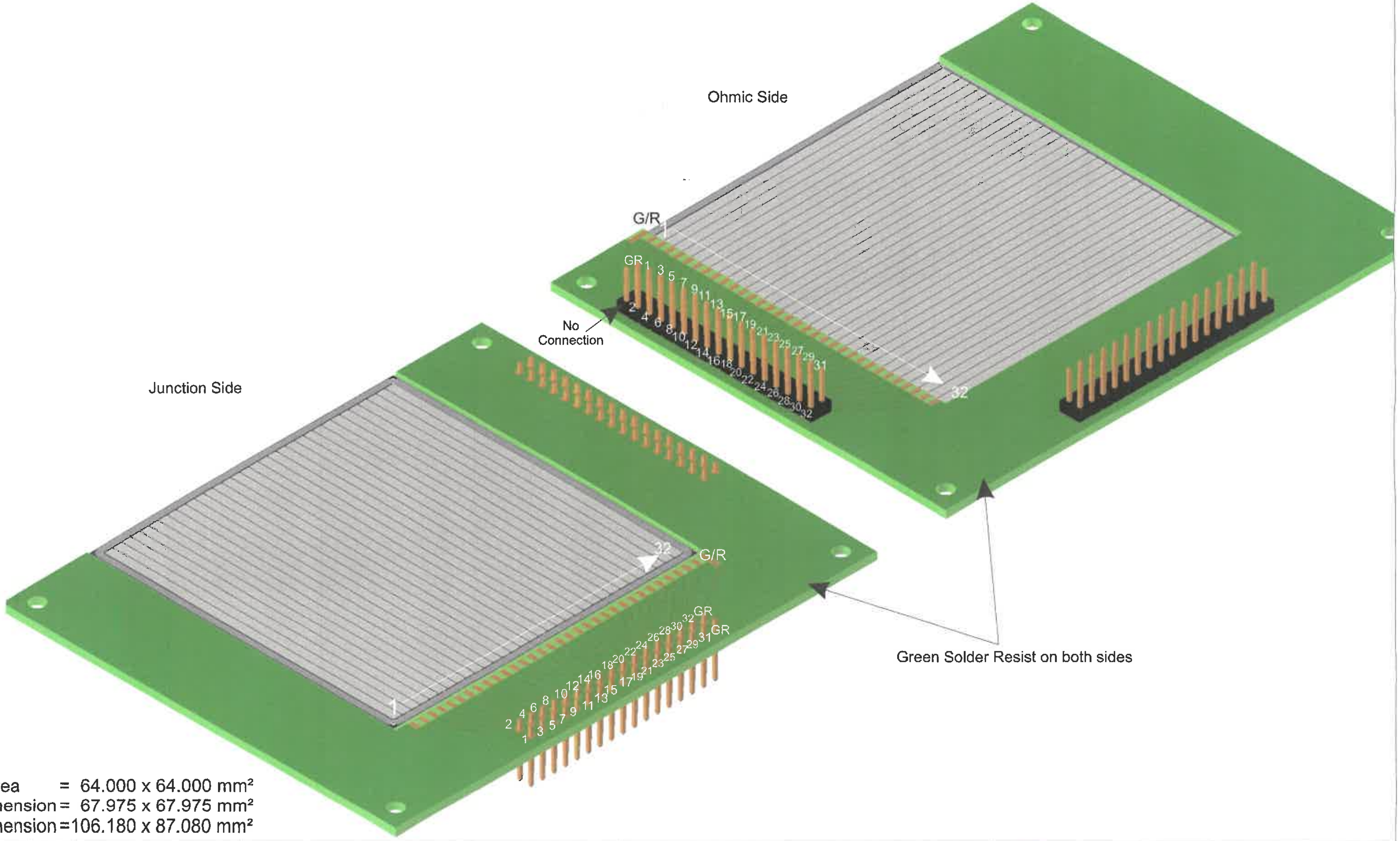
Drg. No A-3451



Active Area = 64.000 x 64.000 mm^2
Chip Dimension = 67.975 x 67.975 mm^2
PCB Dimension = 106.180 x 87.080 mm^2

Drawn	Checked	Date	Tolerances Unless Stated	Outputs Via: Samtec Pt number TSW-117-07-G-D
N.W	S.W	27/11/2007	Package O/D ± 0.1 mm	Mating connector: For Testing purposes Samtec SSW-117-22-G-D-VS
Des. Appd.			Package Hole ± 0.05 mm	Potted Wire Bonds: No
Micron			Package Hole Pos'n ± 0.1 mm	Substrate Number: A-2953
			Detector O/D ± 20.0 µm	Substrate Material: 1.6 mm Thick D/S FR4 Material with Soft Gold on Coppe
				Connector Orientation: Exiting the rear

Title.

BB7(DS)
In 3 Sided PCB.
3D Assembly.

MICRON SEMICONDUCTOR LIMITED

THIS DOCUMENT IS THE PROPERTY OF
MICRON SEMICONDUCTOR LTD AND IS
COMMERCIAL IN CONFIDENCE

graphics@micronsemiconductor.co.uk

Scale N/A	Dims In. mm	Drg No A-3451